

DS-330

Fanless Outdoor System with Intel® Atom® Core™ Processor



Features

- Intel® Atom™ x7433RE, N97, i3 N305 Processor
- Book-sized Fanless System
- 3 Independent Display: HDMI x 2 + USB-C
- Versatile I/O: 2 x LAN, 4 x USB, 2 x COM
- Suitable for outdoor usage: -20 to 60°C wide temperature and 12-24V wide voltage
- Equipped with firmware TPM (fTPM) by default; discrete TPM 2.0 available as a BOM option based on project request

Trellix Acronis WISE-PaaS/SignageCMS WISE-DeviceOn

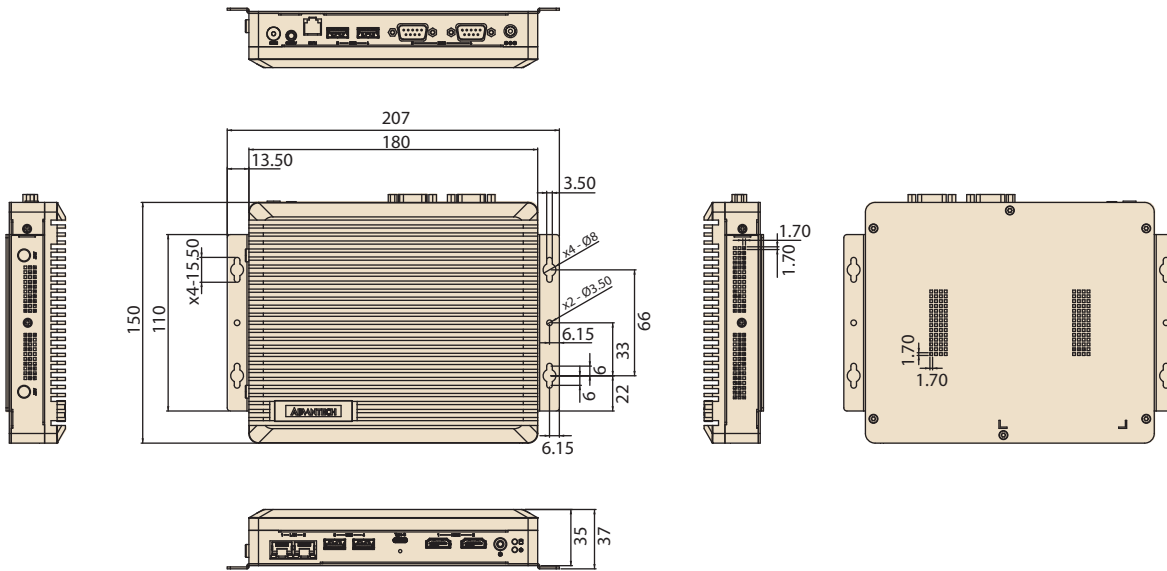
Specifications

Model Name		DS-3300F-U0A1E	DS-3300F-U1A1E	DS-3300F-U2A1E
Processor System	CPU	Intel® Atom™ X7433RE (Amston Lake)	Intel® Atom™ N97 (Alder Lake N)	Intel® Core™ i3-N305 (Alder Lake N)
	Frequency	1.5GHz	2.0GHz	1.8GHz
	Max. Frequency	3.4 GHz	3.60 GHz	3.80 GHz
	Core	4	4	8
	CPU TDP	9W	12W	15W
	System Chipset	Integrated in CPU		
Memory	Technology	DDR5 4800 MHz SODIMM		
	Max. Capacity	16GB		
	Socket	Single Slot		
Thermal Solution	Fanless			
Display	Graphics Engine	Intel UHD graphics		
	Output	HDMI 1 and 2 support up to 4K UHD resolution (HDMI 1 and 2 support HW EDID) USB-C support up to 4K UHD Resolution Supports 2 x 4K UHD and 1 x FHD Resolution in Triple Display scenario		
	Max. Resolution (HDMI 2.1 TMDS)	3840x2160 @60Hz		
	CEC	BOM Option (By project support)		
I/O Interfaces	Ethernet	2 x Intel i226IT (2.5GbE)		
	USB	4 x USB 3.2 Gen1 (Type A), 5V/0.9A 1 x USB-C: Support 1 x DP 1.4a 4K 60Hz + 1 x USB 3.2 Gen1, 5V/3A		
	Serial Ports	2 x 5V/12V Powered COM (RS-232, DB9), (Setting via jumpers; default: 0V)		
	Audio	3.5mm Audio Jack for jack sense (Line-in/out or Mic-in)		
	Function Port	1 x EDID Reset Button		
	Other	12V RJ12 for cash drawer		
	LED Indicators	1 x Power, 1 x Storage Access		
Expansion	M.2	2242 M-Key (SATA/PCIe x2) 2230 E-Key (PCIe & USB2.0) ^{#1}		
	Power Requirement	ACPI 3.0 12 - 24V DC-in (ATX/AT mode)		
Trusted Platform Module	TPM2.0	fTPM 2.0, Default TPM 2.0 (NPCT764AABYX), BOM option by project support		
Watchdog Timer	Output	Interrupt, system reset		
	Interval	255-level timer interval, setup by software		
Physical Characteristics	Mounting	Wall Mount		
	Dimensions (W x D x H)	180 x 150 x 35 mm		
	Weight	1.27kg		
Environment	Operating Temperature	-20 ~ 60°C / -4 ~ 140°F (with 0.7m/s air flow)	0 ~ 60°C / -32 ~ 140°F (with 0.7m/s air flow)	0 ~ 60°C / -32 ~ 140°F (with 0.7m/s air flow)
	Relative Humidity	95% @ 40°C (non-condensing), operating		
Operating System	Operating System	Windows 11 IoT, Windows 10 IoT		
	Linux	supported by project		
Certifications	EMC	CE/FCC Class B, BSMI, CCC		
	Safety	UL, CB, BSMI, UKCA, CCC		

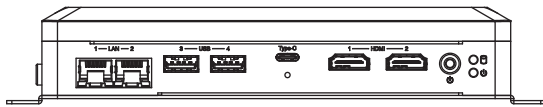
#1 M.2 E key slot are hardware interfaces for wireless communication integration only. RF Certification is not available.

Dimensions

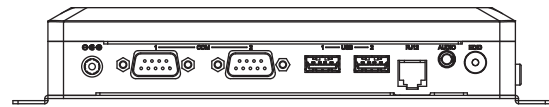
Unit: mm



Front View

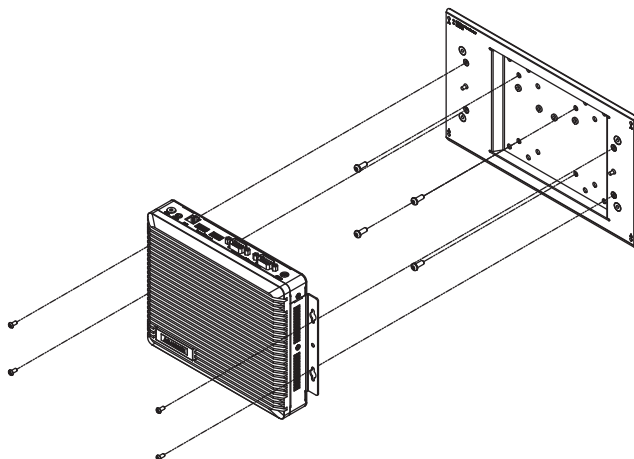


Rear View

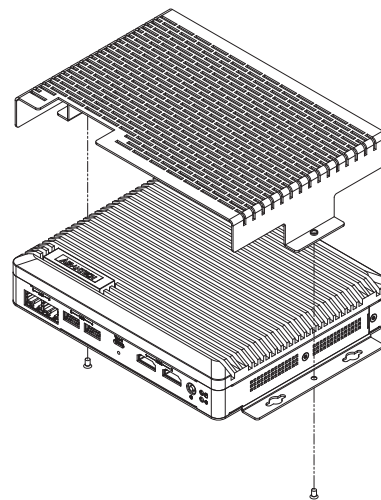


Installation Scenarios

VESA Mount



Protective Cover



Ordering Information

Part No.	CPU	TDP	RAM	Display	LAN	USB	COM (RS-232)	RJ12	M.2	Power Input	TPM 2.0	Made In
DS-3300F-U0A1E	x7433RE	9W	Up to 16GB	2 x HDMI 1 x USB-C	2 x Intel i226IT (2.5G)	4 x USB 3.2 Gen 1 1 x USB-C: Support DP 1.4a + USB 3.2 Gen 1	2 x COM: RS-232 (Powered)	1 x RJ12	1 (SATA/PCIex2)	12-24V DC-IN	N	China
DS-3300F-U0A1U											N	Taiwan
DS-3300F-U1A1E	N97	12W									N	China
DS-3300F-U1A1U											N	Taiwan
DS-3300F-U1A2E											Y	China
DS-3300F-U2A1E	i3 N305	15W									N	China
DS-3300F-U2A1U			N	Taiwan								

Note: RAM / Storage and Operating System bundled by request

Packing List

Part Number	Description
-	1 x DS-330
96PSA-A65W19V1-3	1 x 19V Power adapter
1990023486N001	5 x Thermal PAD for CPU/SSD/WIFI
1990025595N000	2 x Thermal PAD for Memory

Embedded OS

Part Number	Description
20706WLE1S0097	Win11 IoT LTSC EN, 64b Entry
20706WX1ES0149	Win10 IoT LTSC EN, 64b Entry
20706U24DS0041	Ubuntu Desktop 64b 24.04
20706U24ES0006	Ubuntu Pro 64b 24.04

RAM and Storage

Part Number	Description
SQR-SD5I8G5K6SNGPB	RAM DDR5 4800 8GB W.T. (Samsung)
SQR-SD5I16G5K6SNPB	RAM DDR5 4800 16GB W.T. (Samsung)
SQR-SD5I16G5K6HNAG	RAM DDR5 4800 8GB W.T. (Hynix)
SQR-SD5I32G5K6HNAG	RAM DDR5 4800 16GB W.T. (Hynix)
SMI-SD5V8GN56-CC	Semi Ind DDR5 5600 8GB, 0 ~85
SMI-SD5V16GN56-CB	Semi Ind DDR5 5600 16GB 0 ~85
SQF-C4MV2-128GDDEM	Storage M.2 NVMe 2242 TLC 128GB W.T.
SQF-C4MV2-256GDDEM	Storage M.2 NVMe 2242 TLC 256GB W.T.
SQF-C4MV2-512GDDEM	Storage M.2 NVMe 2242 TLC 512GB W.T.
SQF-C4MV4-1TDDEM	Storage M.2 NVMe 2242 TLC 1TB W.T.
SQF-S4BV1-128GDSDM	Storage M.2 SATA 2242 TLC 128GB W.T.
SQF-S4BV1-256GDSDM	Storage M.2 SATA 2242 TLC 256GB W.T.
SQF-S4BV2-512GDSDM	Storage M.2 SATA 2242 TLC 512GB W.T.
SQF-S4BV2-1TDSDM	Storage M.2 SATA 2242 TLC 1TB W.T.

Note: RAM and storage listed in the table are wide temp. version. Standard temp. options are also available by request.

Power Cord

Part Number	Description
1700001524	3-pin power cord (US)
170203183C	3-pin power cord (EU)
170203180A-01	3-pin power cord (UK)
1700008921	3-pin power cord with PSE (Japan)
1700019146	3-pin power cord (CCC)
1700018553	3-pin power cord (AU)
1700024849-01	3-pin power cord (TW)

Optional Items

Part Number	Description
1960056999T301	DS-330 VESA Mount
1960119683N001	DS-330 Protective Cover
1960120182N001	DS-330 Pole Mount Bracket
AMK-V025E	DS-330 Mounting Kit (VESA/Pole Mount Bracket/Adapter Kit)
AIW-170BQ-001	Qualcomm WiFi6E M.2 2230 E key
1751000648-01	1 x Cable Ant. 100mm (usage:2 pcs)
AIW-512	2 x Antenna

Note: If Wi-Fi is required, the package must include the module, antenna, and antenna cable.